## Pro2 Series Technical Specifications

Raise3D Pro2 Series are dual extruder 3D printers with high-resolution, for manufacturing and rapid-prototyping projects of varying sizes. They are designed to print complex parts, support a variety of filaments and improve print speed, and recognized as the benchmark and gold standard for serious 3D printing applications and 24/7 reliability.

Printer	Raise3D Pro2			Raise3D Pro2 Plus			
	Single Extruder Print		Dual Extruder Print	Single Extruder	Single Extruder Print Dua		
Build Volume (W × D × H)	305 × 305 × 300 mm (12 × 12 × 11.8 inch)		280 × 305 × 300 mm 11 × 12 × 11.8 inch)	305 × 305 × 60 (12 × 12 × 23.8		280 × 305 × 605 mm (11 × 12 × 23.8 inch)	
Machine Size (W × D × H)	620 × 590 × 76	0 mm (24.4 × 2	3.2 × 29.9 inch) 620 × 590		× 1105 mm (24.4 × 23.2 × 43.5 inch)		
Weight	Net Weight	Gross Weight (Carton Only)	Gross Weight (Carton with Pallet)	Net Weight	Gross Weight (Carton Only)	Gross Weight (Carton with Pallet)	
	49.9 kg (110.1 lbs)	61.4 kg (135.4 lbs)	68.9 kg (151.9 lbs)	59.5 kg (131.2 lbs)	72.7 kg (160.3 lbs)	80.2 kg (176.9 lbs)	
Electrical	Power Supply Input 100-240 V AC, 50/ 60 Hz 230 V @ 3.3 A Power Supply Output 24 V DC, 600 W						
General	Print H Filame X Print Head T Max Build Plate T Heated E Build Pl Filament Run L Nozz Max Nozzle T Noise Emissic Operating Ambient T Storage T	Bed Material late Leveling nout Sensor Layer Height late Diameter Temperature Connectivity on (Acoustic)	Fused Filament Fabrication (FFF) Dual-head with Electronic Lifting System 1.75 mm 0.78125, 0.78125, 0.078125 micron 15-150 mm/s Heated Aluminum Build Plate with Magnetic Holding 110°C Silicone Pre-calibrated Leveling Available The Pro2 Series is compatible with 0.2, 0.4, 0.6, 0.8 and 1.0 mm nozzles, and the layer height can vary between 0.05-0.6 mm. To achieve stable print results, when using 0.4 mm nozzles, we recommend using a layer height between 0.1-0.3 mm. 0.4 mm (Default), 0.2/ 0.6/ 0.8/ 1.0 mm (Available) 300°C Wi-Fi, LAN, USB Port, Live Camera < 50 dB (A) When Building 15-30°C, 10-90% RH, non-condensing -25°C to +55°C, 10-90% RH, non-condensing HEPA Filter with Activated Charcoal CB, CE, FCC, RoHS				
Material		Material Type arty Material	PLA/ ABS/ ASA/ PETG/ PC/ PETG ESD/ TPU 95A/ PVA+ Supported by Raise3D OFP (Open Filament Program)*				
Software	Supporte Su	ng Software ed File Types upported OS e Code Type	ideaMaker STL/ OBJ/ 3MF/ OLTP Windows/ macOS/ Linux GCODE				
Printer Controller	User Interface Network Network Wi-Fi, Ethernet  Power Loss Recovery Screen Resolution Motion Controller Logic Controller Memory Onboard Flash OS Embedded Linux Ports Vi-Fi, Ethernet Available 1024 × 600 Atmel ARM Cortex M7.400 MHZ FPU NXP i.MX6, Quad core 1 GHz ARM processor 1 GB Os Embedded Linux USB 2.0 × 2, Ethernet × 1						

 $<sup>*</sup> For detailed information and slicing profiles of the materials supported by Raise 3D OFP, please visit $$ \underline{https://www.ideamaker.io/.} $$$ 

